WHAT IS CLAIMED IS:

A mechanically actuated airtight device for wafer carrier, comprising:

a cover, having a first face and a second face, and being formed with at least one hole therethrough;

at least one sealing gasket, being positioned above the hole of the cover, the sealing gasket having a base in a form of wedged ramp, and the base having a through opening;

at least one linked plate, having a first face and a second face, the second face being provided with a protuberance on one side, and the first face being provided with at least one wedged ramp, and the wedged ramp having a slope equal to that of the wedged ramp of the base, such that the wedged ramp of the first face of the linked plate mates with the wedged ramp of the second face of the linked plate; and

a driving wheel, having a first face and a second face, the first face being provided with a first guiding groove to allow the protuberance of the linked plate move along the first guiding groove.

A mechanically actuated airtight device for wafer carrier as set forth in claim 1, further comprising a bottom having a first face and a second face, the first face being located beneath the second face of the driving wheel, and the bottom being engaged with the cover.

A mechanically actuated airtight device for wafer carrier as set forth in claim 1, wherein the sealing gasket has a first face on which a rim is formed.

A mechanically actuated airtight device for wafer carrier as set forth in claim 1, wherein at least one of the wedged ramp of the first face of the linked plate and the wedged ramp of the second face of the sealing gasket is made of elastomeric material.

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